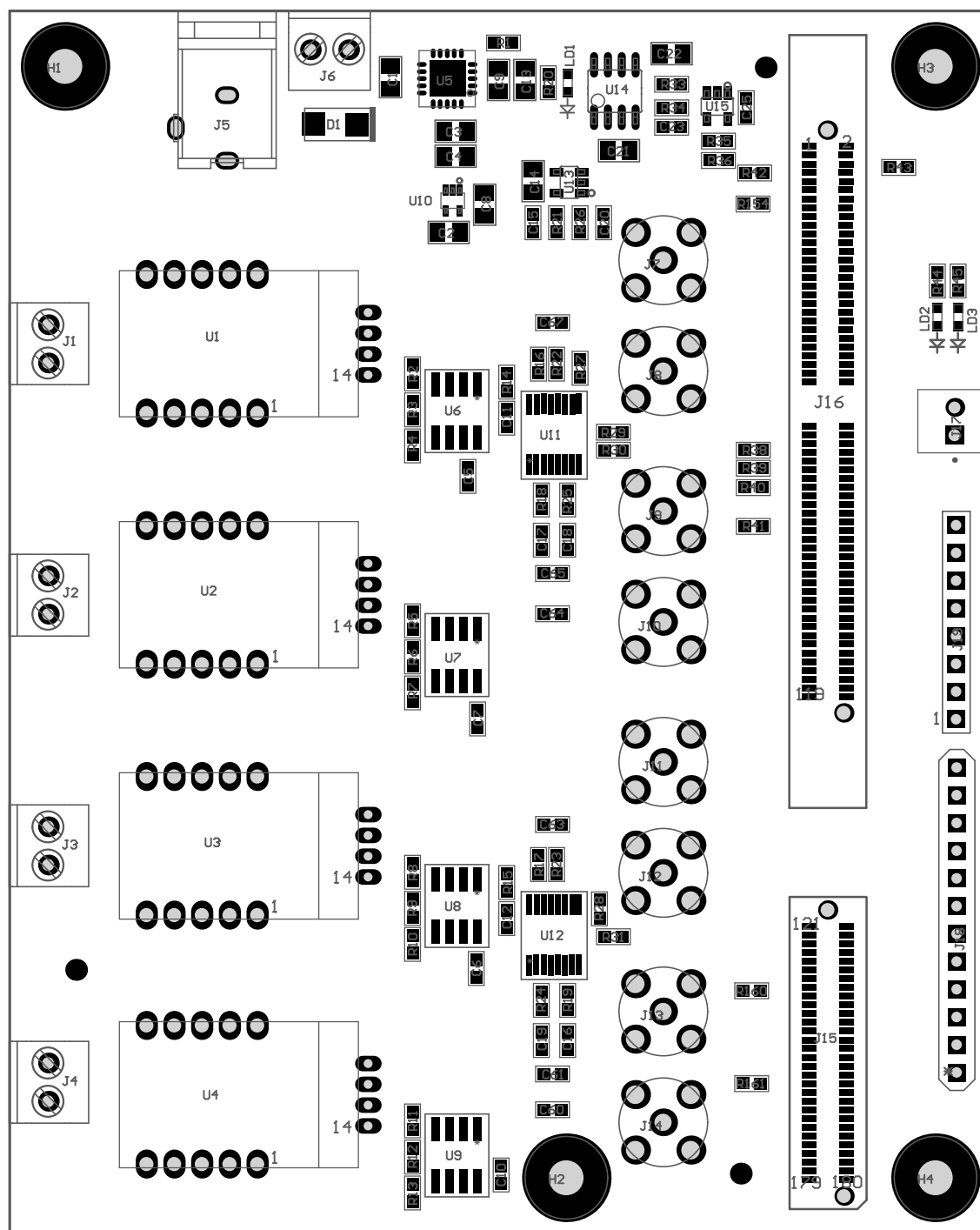


z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

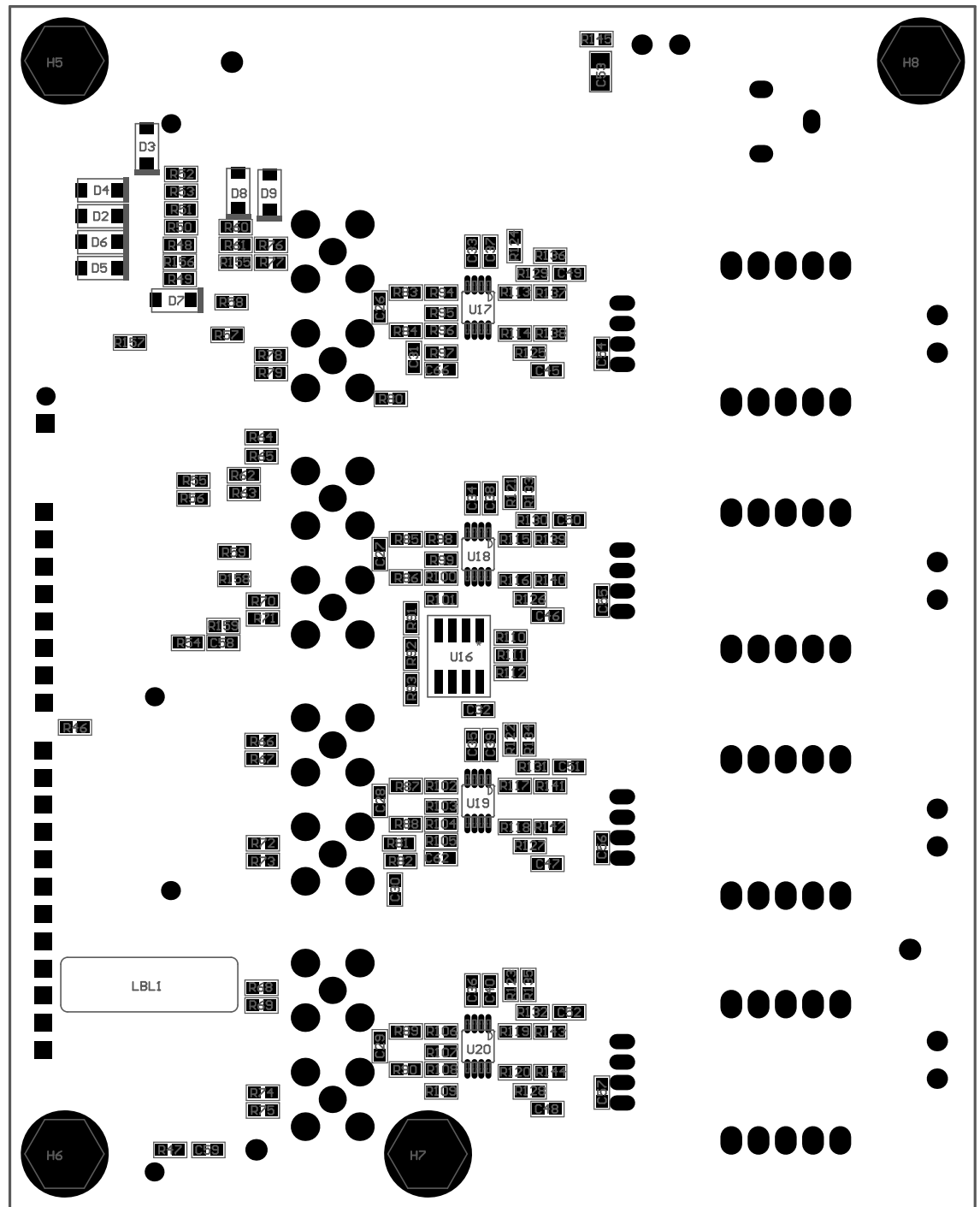
z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00201	REV: E1	SUN REV: Not In VersionControl
IGNORE -> M5 Assembly Top			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/14/2014 4:03:57 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00201	REV: E1	SUN REV: Not In VersionControl
IGNORE ->	M6 Assembly Bottom	Bottom Solder	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/14/2014 4:03:58 PM	TEXAS INSTRUMENTS	

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